GooLED

XSA-327 Pin Fin LED Heat Sink Φ110mm for Xicato

Features VS Benefits

* The XSA-327 Xicato Pin Fin LED Heat Sinks are specifically designed for luminaires using
  the Xicato LED engines.
* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and
  thermal performance matching the lumen packages.
* For spotlight and downlight designs from 2,000 to 5,500 lumen.
* Thermal resistance range Rth 1.47°C/W.
* Xicato Thermal Class **N** , (60° tilt angle, 40°C ambient) .
* Modular design with mounting holes foreseen for direct mounting of Xicato XSA/ XIM/ XTM modules.
* Diameter 110.0mm - standard height 50.0mm,Other heights on request.
* Forged from highly conductive aluminum.

*The XSA-327 Xicato Pin Fin Heat Sink is standard foreseen from a variety of mounting holes which allow direct mounting of all
Xicato Spot and down light LED modules and secondary optics on the Pin Fin LED heat sink.

*In this way mechanical afterwork and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED coolers.

*Below you find an overview of Xicato LED modules which standard fit on the XSA-327 Pin Fin LED Heat Sinks.

*MingFa performs thermal validation tests on each of the LED modules mounted on the LED cooler and publishes.

*This data in the Xicato Cooler thermal validation reports.

*For a full overview of avaliable LED coolers for Xicato LEDs, please refer to the Xicato LED cooler overview on.
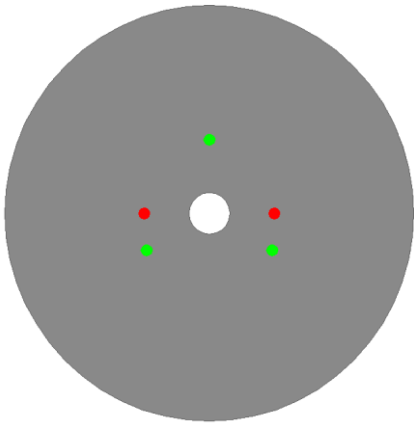
Xicato LED Modules directly Mounting Options

Xicato XSM LED modules name :

XSM8027-xxxx ;	XSM9530-xxxx ;
XSM8030-xxxx ;	XSM9540-xxxx ;
XSM8040-xxxx ;	XSMV830-xxxx ;
XSM9527-xxxx ;	

Direct mounting with 3 screwsM3 x 12mm;
Green indicator marks.

Xicato XIM LED modules name :

XIM198027-xxx ;	XIM198040-xxx ;	XIM09-V9xxxxxx ;
XIM198030-xxx ;	XIM19V830-xxx ;	
XIM198035-xxx ;	XIM0980 xxxxxx ;	

Direct mounting with 3 screws M3 x 20mm;
Green indicator marks.

Xicato XTM LED modules:

XTM19-8027-xxx ;	XTM19-8040-xxx ;	XTM0995 xxxxxx ;
XTM19-8030-xxx ;	XTM19-V830-xxx ;	
XTM19-8035-xxx ;	XTM09-V9xxxxxx ;	

Direct mounting with 3 screws M3 x 10mm;
Green indicator marks.
Direct mounting by Zhaga mounting holes with 2 screws M3 x 8mm;
Red indicator marks.

GooLED

XSA-327 Pin Fin LED Heat Sink Φ110mm for Xicato

Mounting Options and Drawings & Dimensions

Example: XSA-327-M3-B-1

Example: XSA-327-M3- 1 **-** 2

1 **Anodising Color**

B-Black

C-Clear

Z-Custom

2 **Mounting Options - see graphics for**

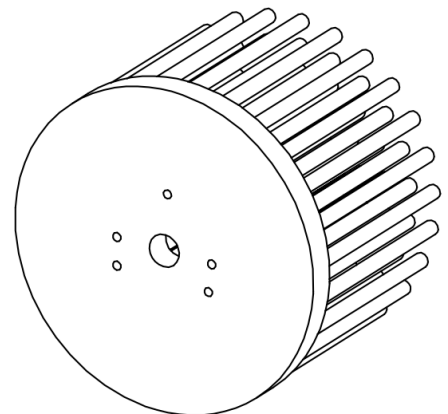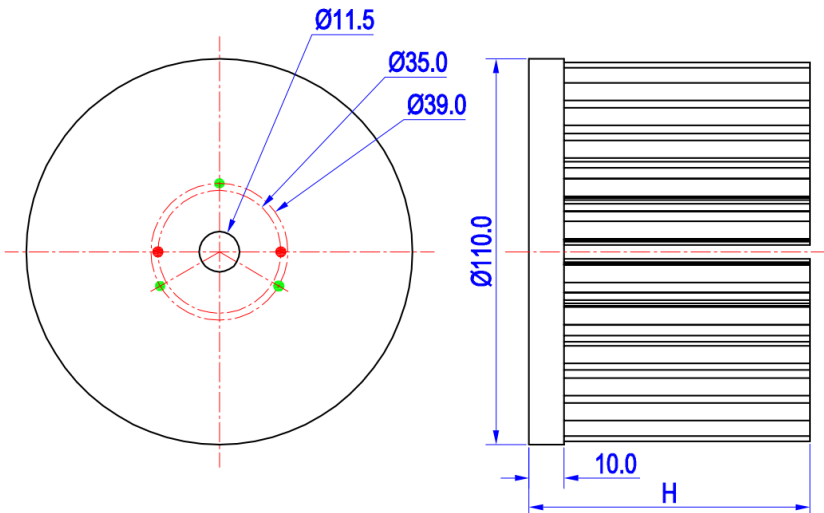**details Combinations available**

Ex.order code - 12

means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.

- For specific mechanical adaptations please contact MingfaTech.

- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	PART NUMBER	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
N	XSA-327-M3-#-N	M3	6.5mm	39.0mm/ 3-@120°
1	XSA-327-M3-#-1	M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
2	XSA-327-M3-#-2	M3	Φ11.5mm	Through-Hole

Tel:+86-769-39023131
Fax:+86-(020)28819702   ext:22122
Email:sales@mingfatech.com
Http://www.heatsinkled.com
Http://www.mingfatech.com

Mingfa Tech

2

GooLED

XSA-327 Pin Fin LED Heat Sink Φ110mm for Xicato

The product deta table

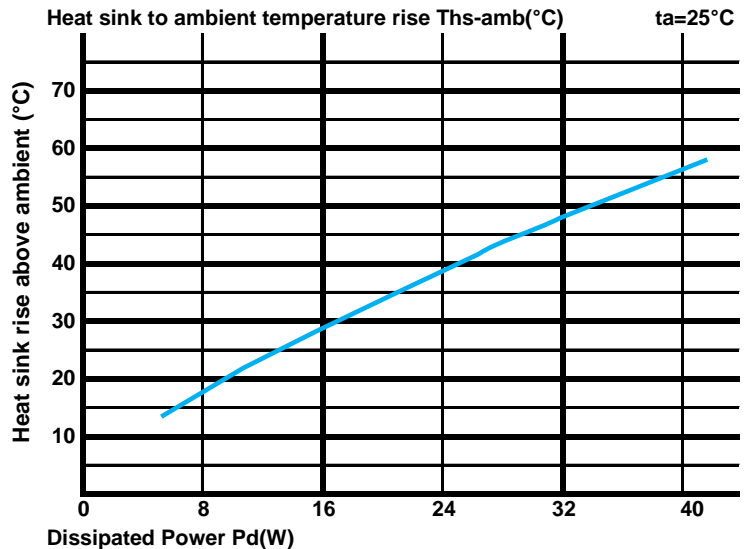| Model No.	XSA-327
Heatsink Size	Φ110xH50mm
Heatsink Material	AL1070
Finish	Black Anodized
Weight (g)	463.0
Dissipated power (Ths-amb,50℃)	34.0 (W)
Cooling surface area (mm²)	83372
Thermal Resistance (Rhs-amb)	1.47 (°C/W)

The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		XSA-327	
Dissipated Power Pd(W)	8.0	2.25	18.0
	16.0	1.81	29.0
	24.0	1.63	39.0
	32.0	1.50	48.0
	40.0	1.40	56.0

Heat sink to ambient temperature rise Ths-amb(°C)   ta=25°C

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.
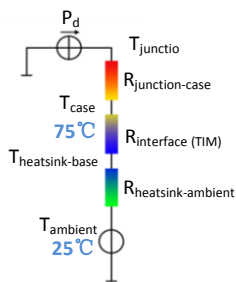
*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: θ ＝(Ths－Ta)/Pd

θ - Thermal Resistance [°C/W] ;   Ths - Heatsink temperature ;   Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}＝(R_{junction-case}＋R_{case-ambient})·Pd＋T_{ambient}$